

# Micro-Raman Spectroscopy Measurement of Stress in Silicon

Sergej Shashkov, SOL instruments Ltd.,  
Nezavisimosti ave.58-10, Minsk, Belarus

Mechanical stress can have direct or indirect effects on the functioning and reliability of a chip and can cause different failure modes, such as:

- changes in electron or hole mobility
- dislocations near isolation structures
- cracks in chips,
- creep in metals,
- stress migration, etc.

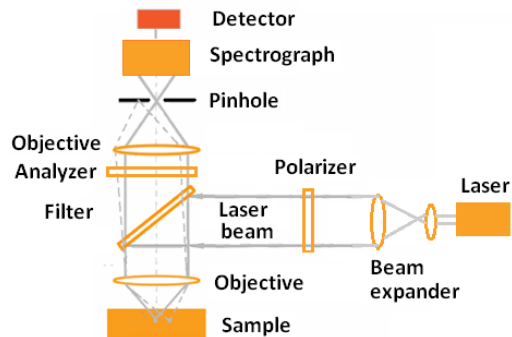
Stress can also be used in a positive way, for example to increase the carrier mobility.

## Local Strain Metrologies

method	sensitivity $\epsilon$ : strain	Spatial resolution	feature
<b>Raman scattering</b>	<b><math>0.05 \text{ cm}^{-1}</math> (<math>\epsilon \sim 0.005\%</math>)</b>	<b><math>\sim 130 \text{ nm}</math></b>	<b>Non-destructive Non-contact</b>
<b>CBED</b> (Convergent beam electron diffraction)	<b><math>\Delta d/d = 0.02\%</math></b>	<b><math>\sim 20 \text{ nm}</math></b>	<b>High precision</b>
<b>NBD</b> (Nano-beam electron diffraction)	<b><math>\Delta d/d = 0.1\%</math></b>	<b><math>\sim 10 \text{ nm}</math></b>	<b>High spatial resolution</b>

T. Kanayama, 2007 Int Conf Frontiers of Characterization and Metrology for Nanoelectronics, March 29, 2007

# Confotec family



Confotec® MR350



Confotec® MR520



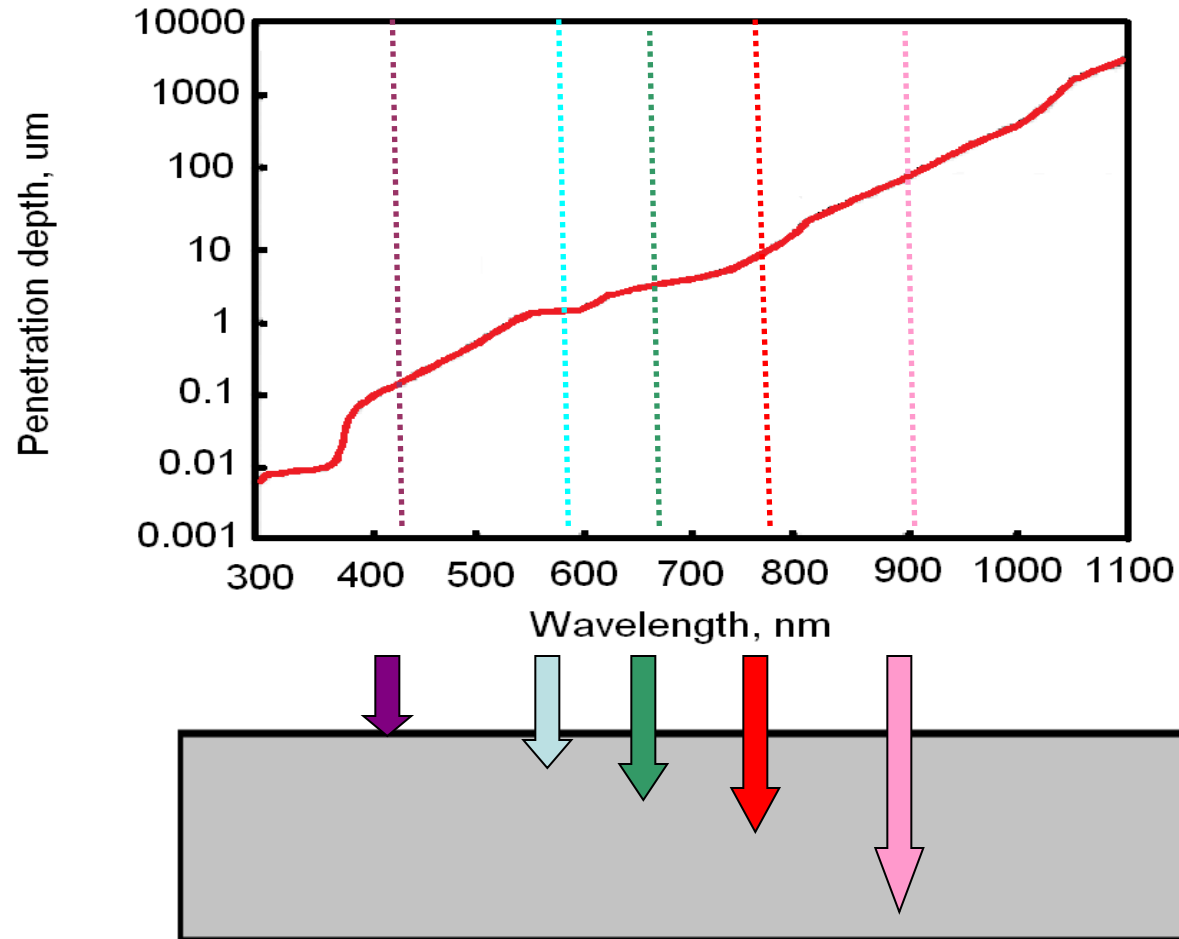
Confotec® NR500



Confotec® CARS

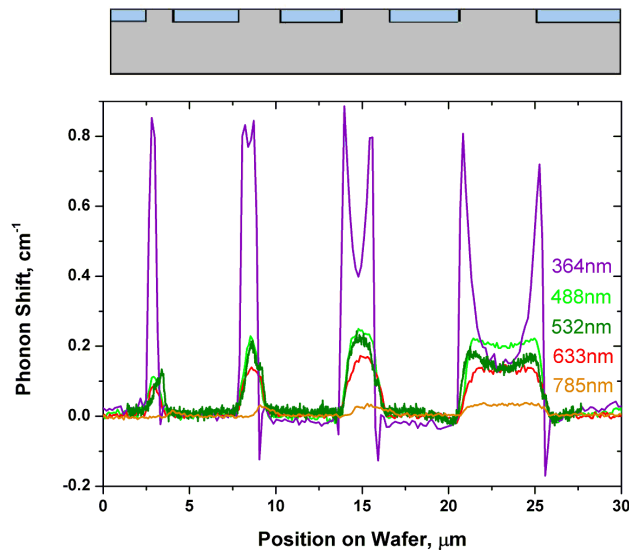
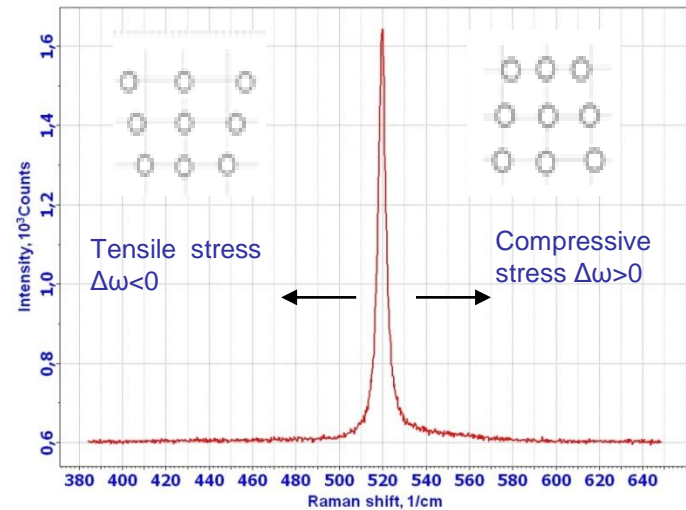


## Penetration Depth

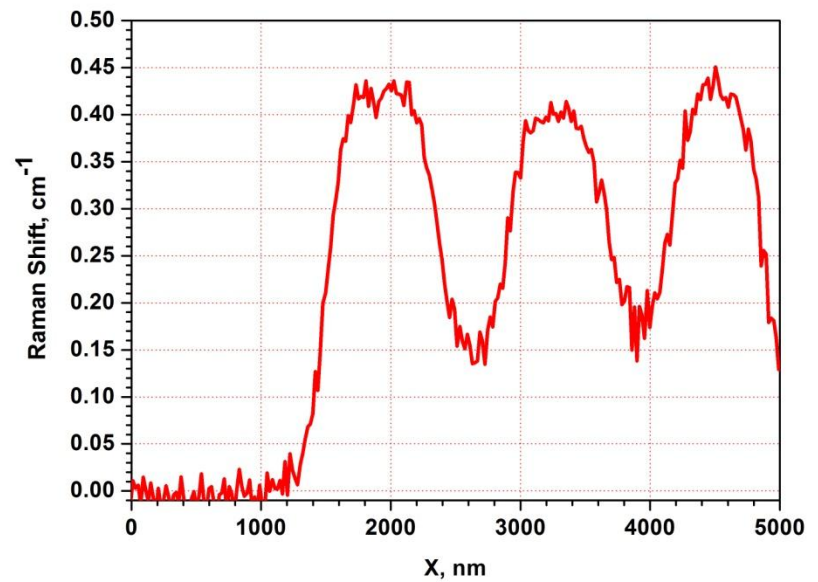
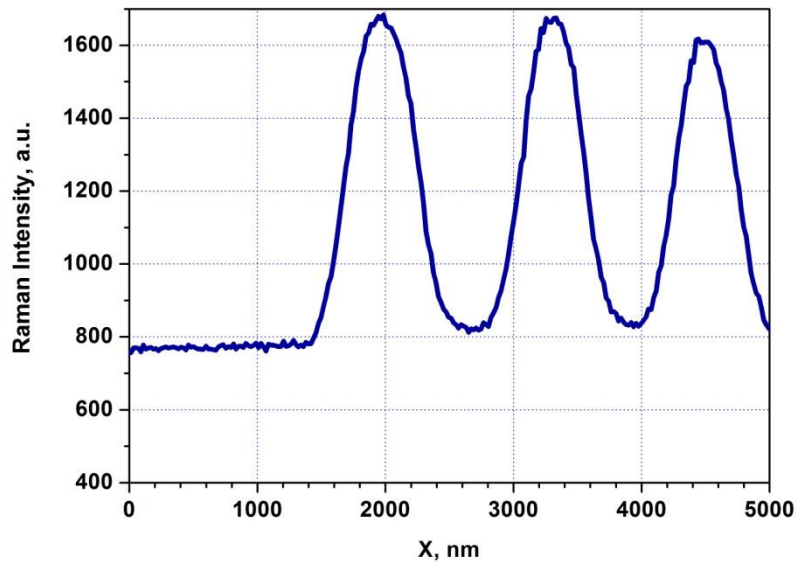
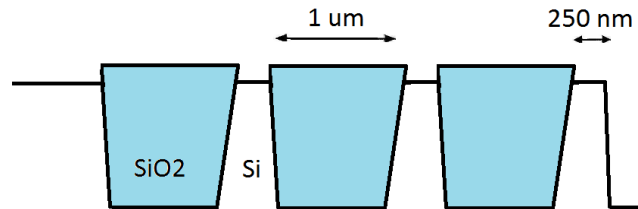


The next equation can be applied to the Si stress monitoring:

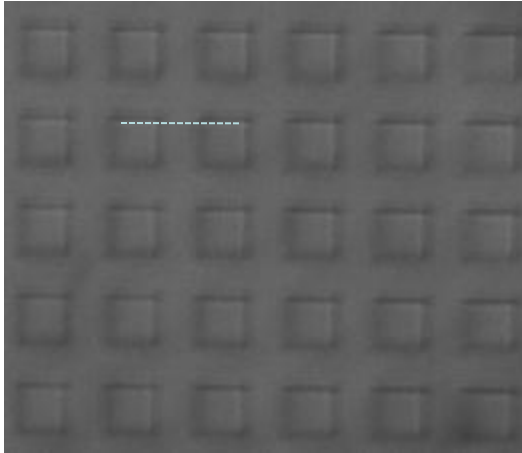
$\sigma(\text{MPa}) = -435 \cdot (\omega - \omega_0) (\text{cm}^{-1})$ ,  
 where  $\sigma$  is the stress value,  
 $\omega_0 = 520.5 \text{ cm}^{-1}$  is the peak position of the stress-free state,  $\omega$  is the Si peak position at the stressed state.



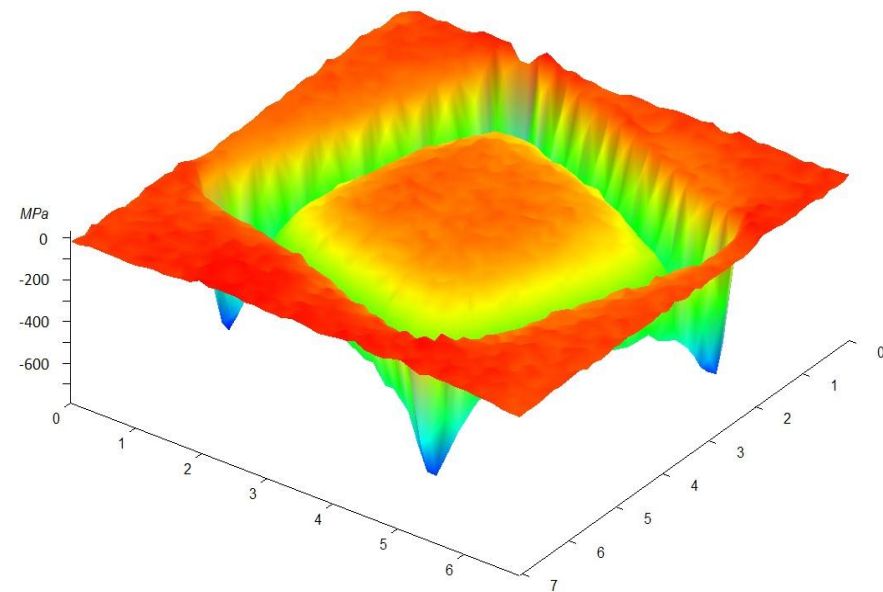
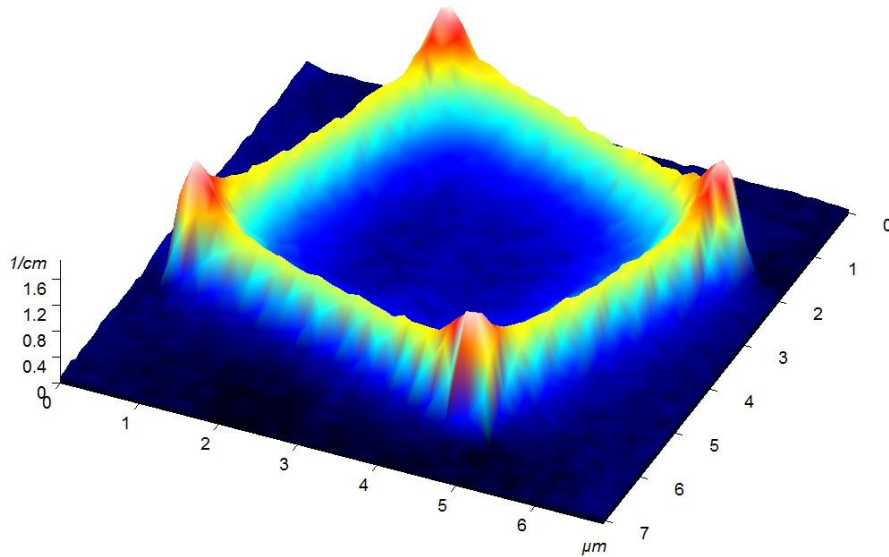
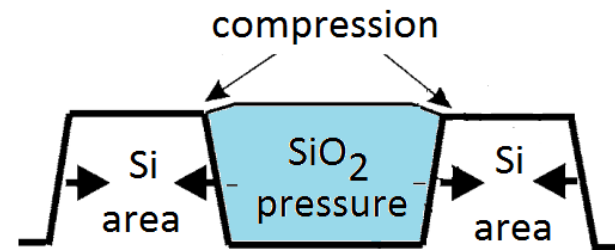
The sample consists 1, 1.5, 2 and 4  $\mu\text{m}$  wide Si stripes separated by 4  $\mu\text{m}$  shallow trenches.



1sec/point; 532nm laser; ~2 mW laser power, 20nm scanning step



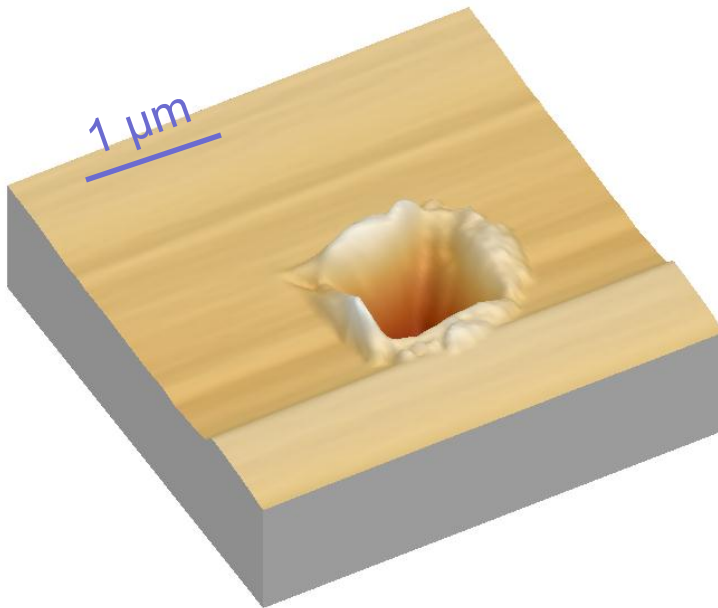
A periodic STI (shallow trench isolation) structure



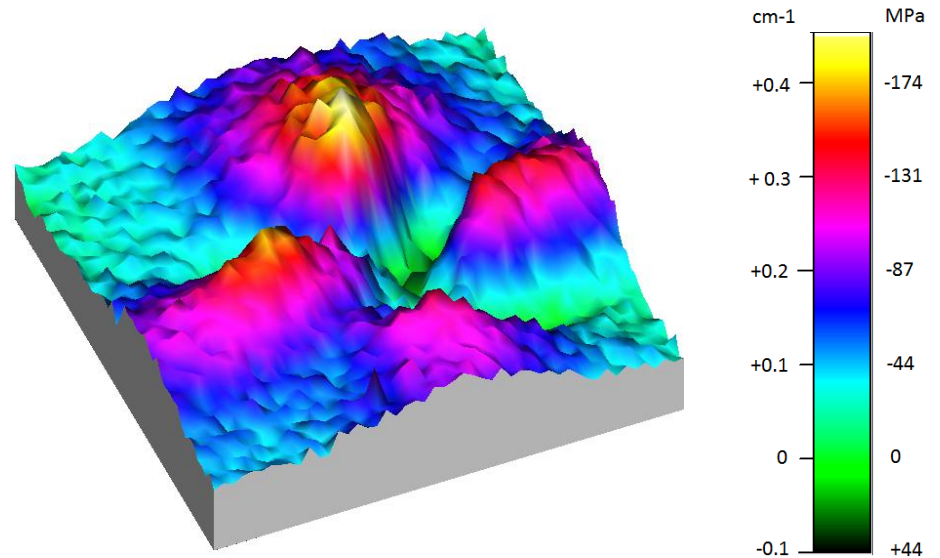


## Defect Area on the Silicon Wafer

AFM

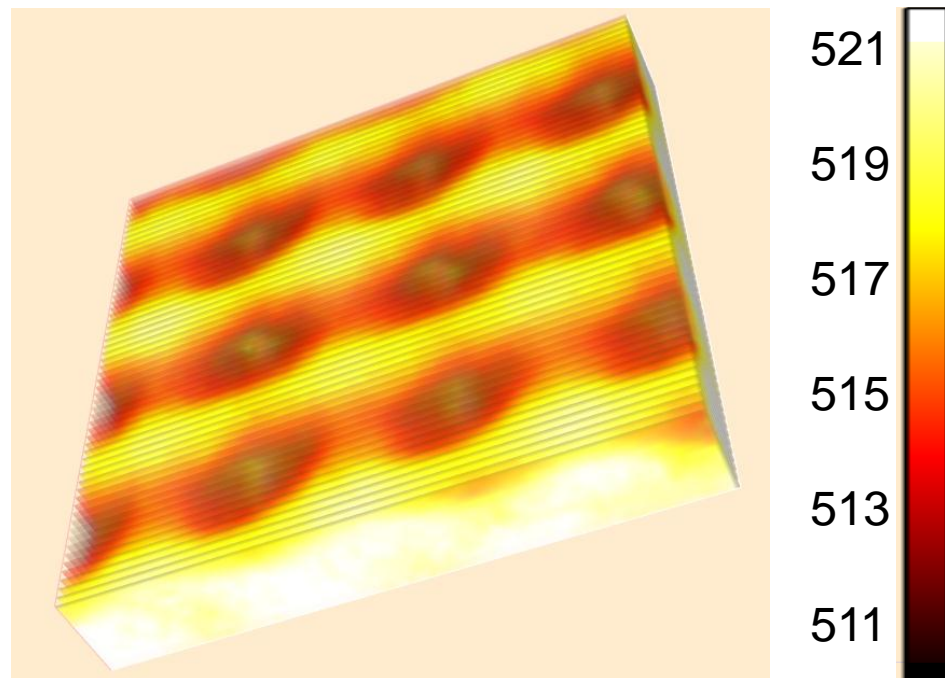
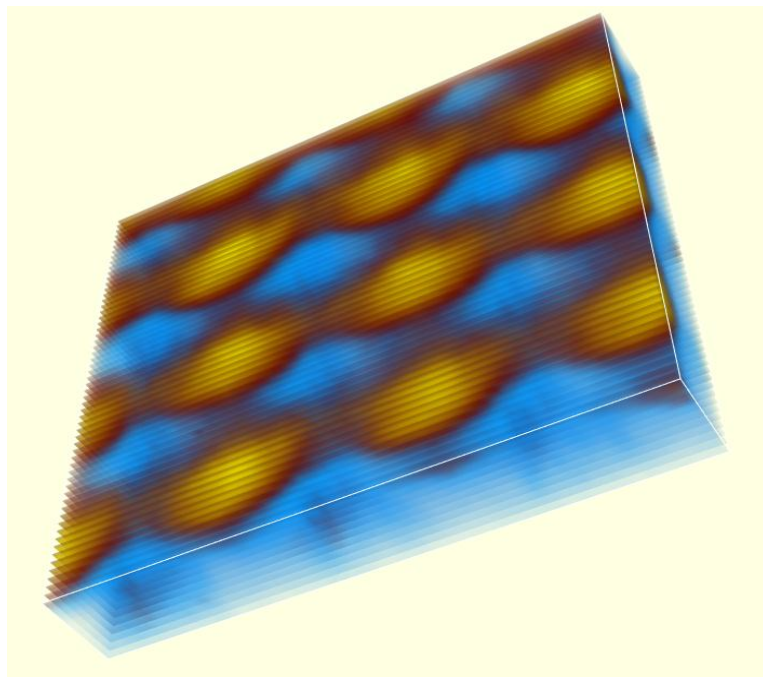
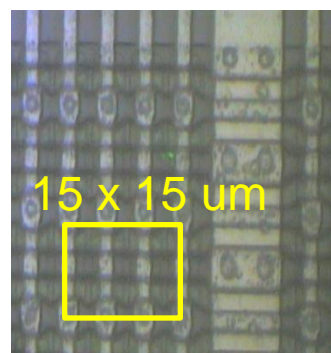
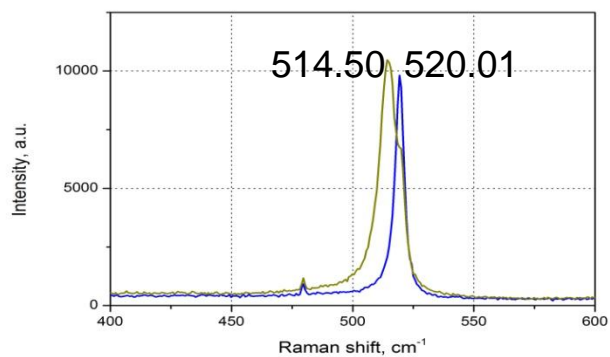


Stress Distribution



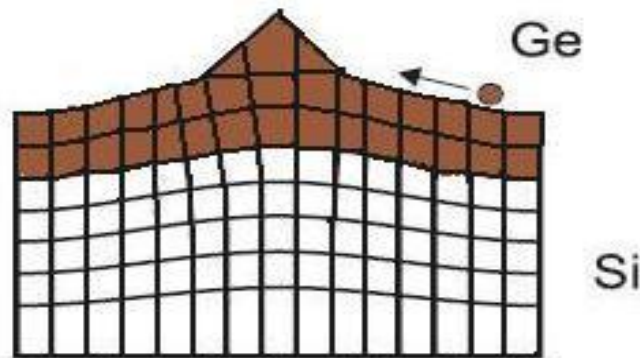
Variation of stress lies in the range between +43 MPa and -175 MPa.

## EEPROM Investigation

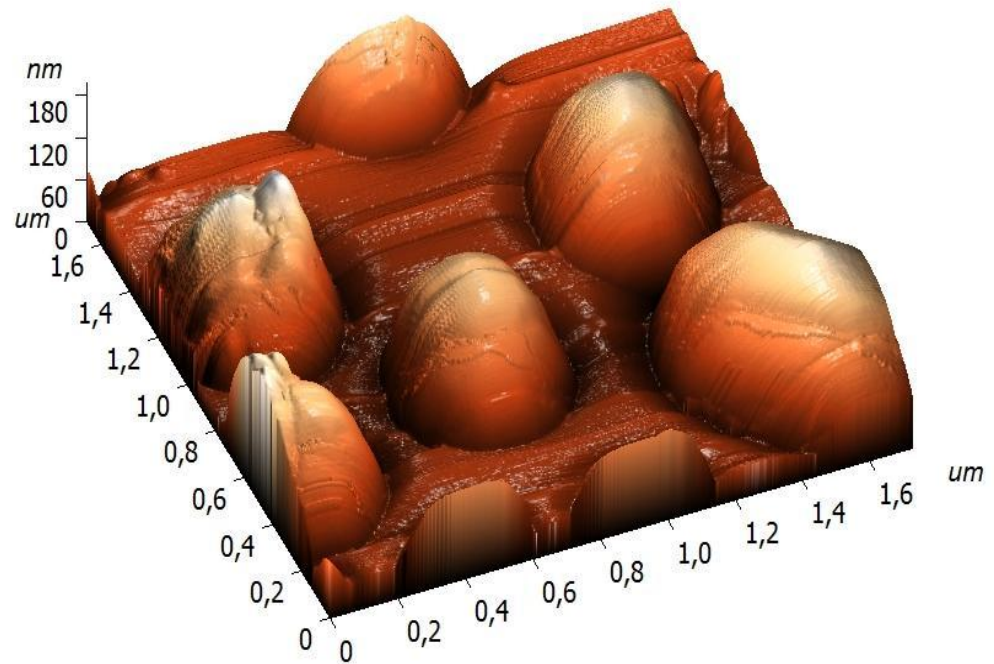


## Ge QD on a Silicon Substrate

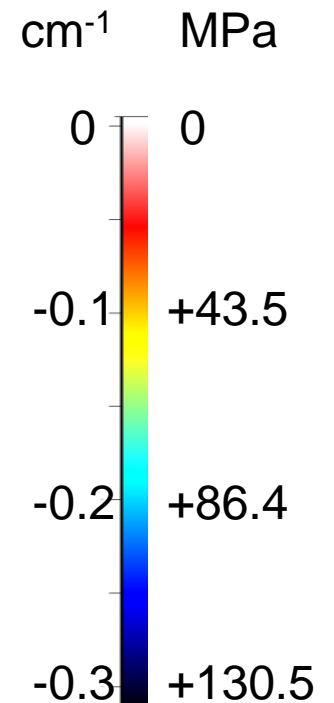
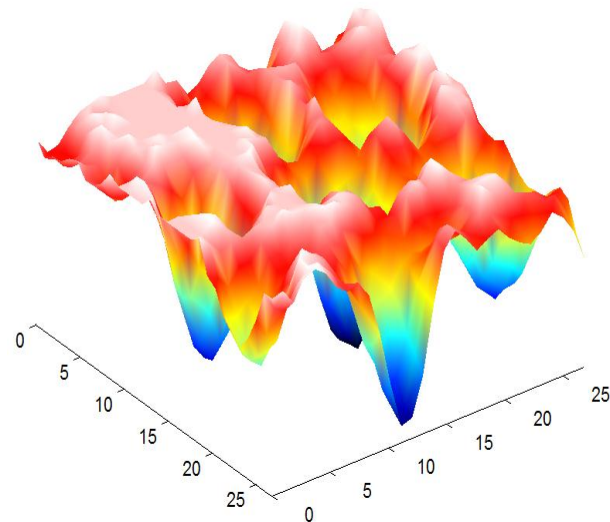
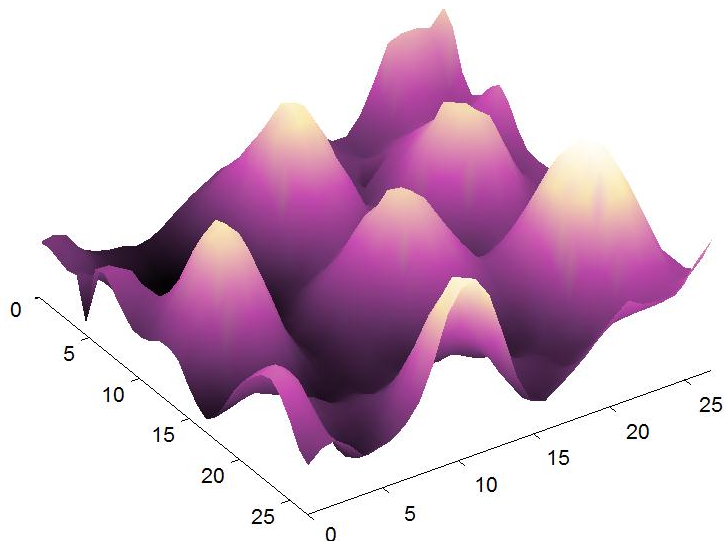
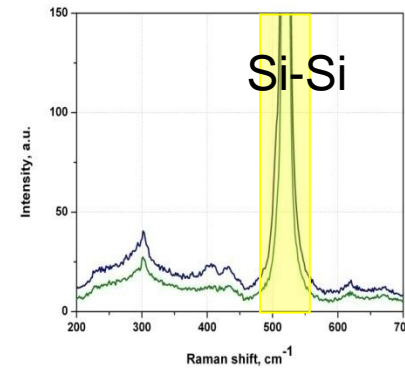
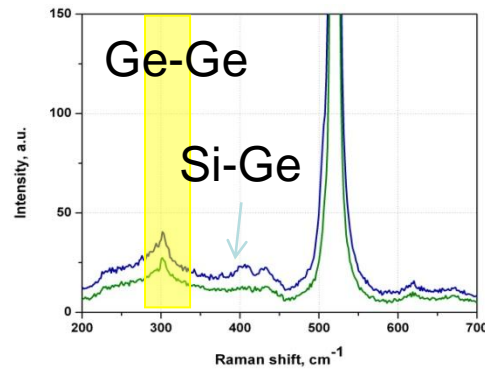
Growing of Ge dots on Si Substrate  
(schematic diagram)



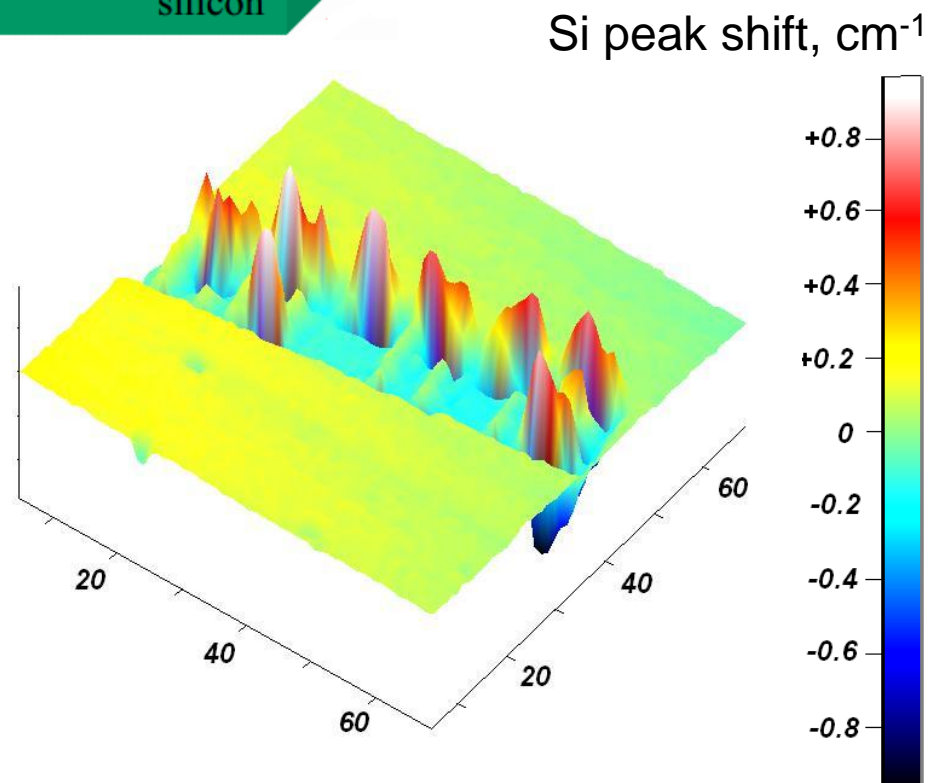
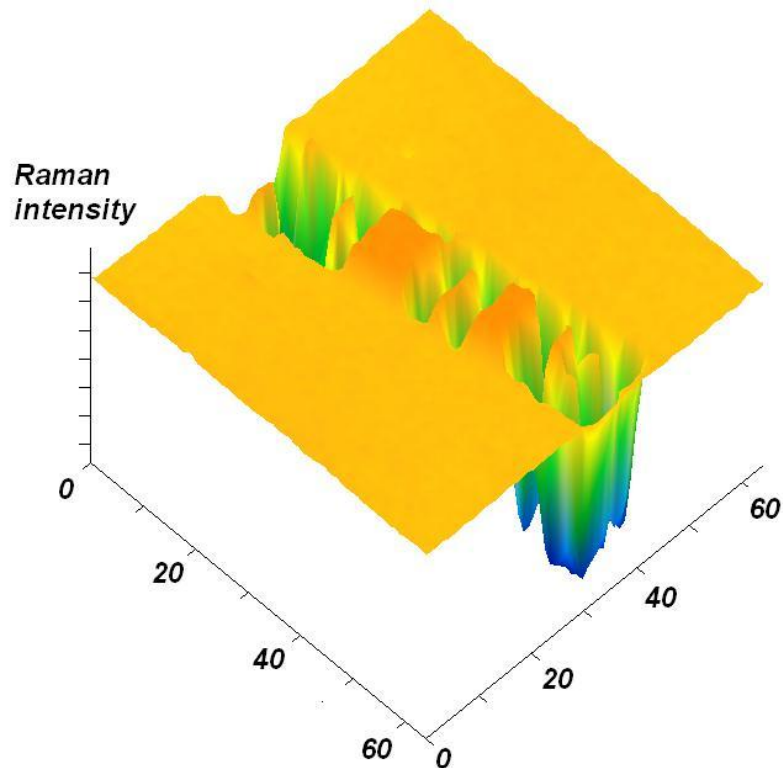
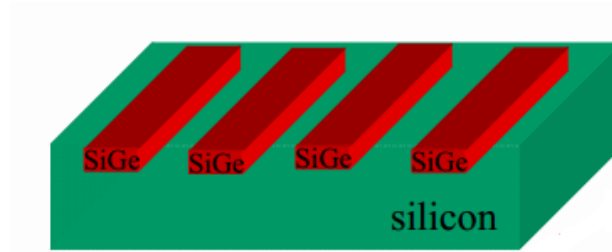
AFM Topography



## Raman Microscopy of Ge dots on Si

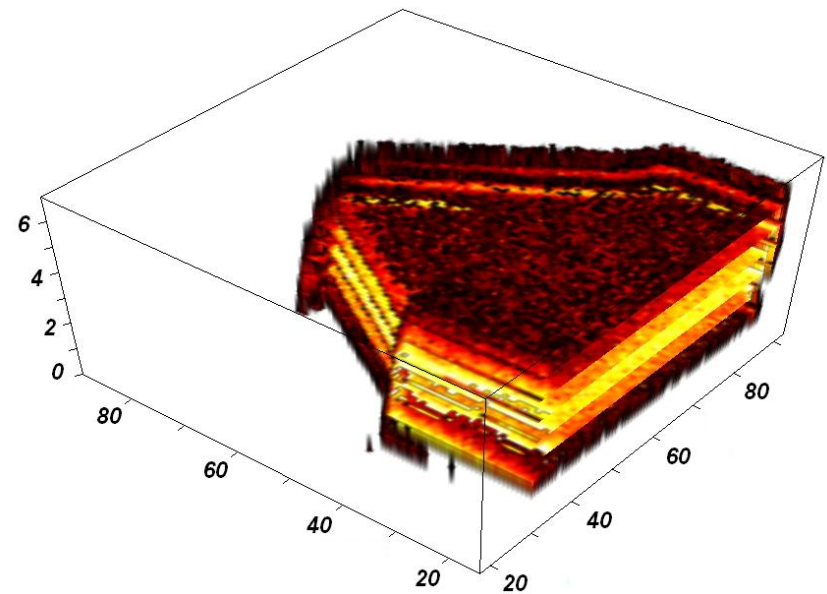
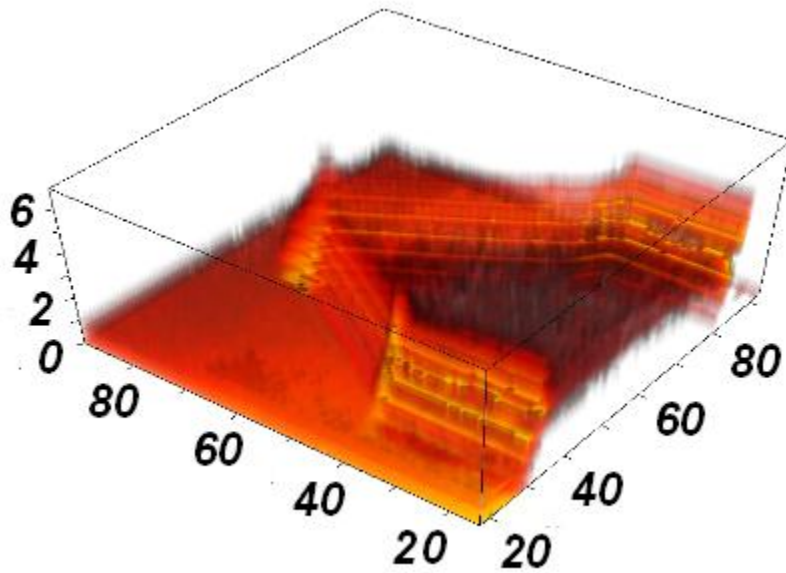


## Strain Investigation in a SiGe Sample





## AFM Cantilever: Raman Imaging





Thank you very much for your attention!